

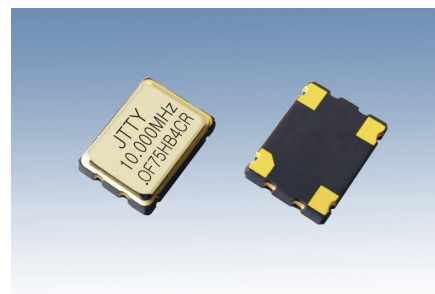
Series Miniature Ceramic SMD Tristate Oscillator HCMOS/TTL Compatible

产品特点 FEATURES

- 典型的7.0X5.0X1.3mm 陶瓷底座贴片封装  
Typical 7.0X5.0X1.3mm ceramic SMD package
- 三态启用/禁用 Tri-state enable/disable
- 高达125°C工作温度范围  
Up to 125°C operating temperature range
- 可回流焊接  
Can reflow

应用范围 APPLICATION

- xDSL、WLAN、光纤  
xDSL、WLAN、Fiber
- 10G以太网 10G-Bit Ethernet  
笔记本、PDA  
Notebook、PDA
- 电脑主板、VGA卡  
PC main board、VGA card



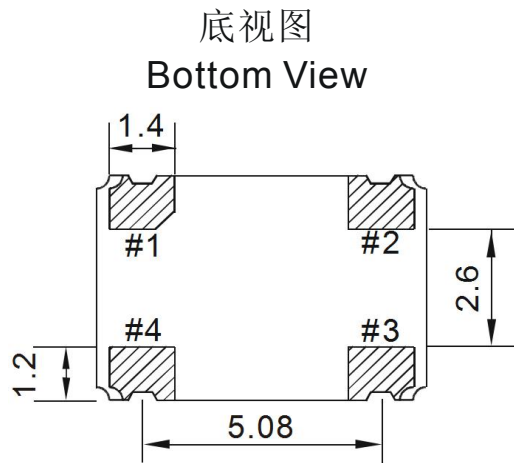
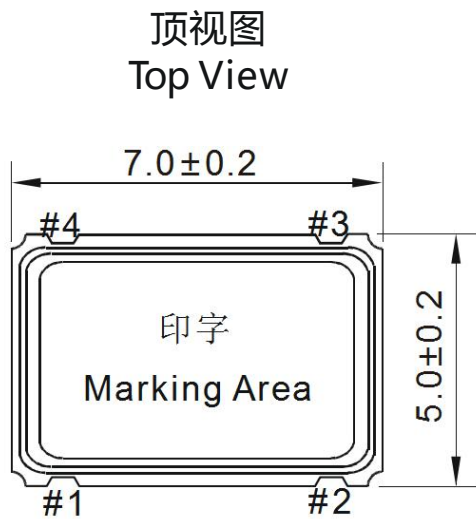
参数 Parameter	符号 Sym.	条件 Condition	最小值 Min.	典型 Typ.	最大值 Max.	单位 Unit	备注 Note
输入电压范围 Input Break Down Voltage	Vcc		-0.5		+5.0	V	
存储温度 Storage Temp.	Ts		-55		+125	°C	
频率范围 Frequency Range	F		32.768KHz~220MHz				
标称频率 Nominal Frequency	Fn					MHz	自定义 Custom
频率精度 Frequency Tolerance	ΔF/F	@25°C	±5		±50	ppm	
频率稳定度 Frequency Stability	ΔF/F		±5		±100	ppm	注 1 Note 1
工作温度范围 Operating Temp. Range			-20 ~ +70		°C	标准 Standard	
			-40 ~ +85			工业控制 Extended	
			-55 ~ +125			汽车及军工 Car&Military	
存储温度 Storage Temp.Range			-55 ~ +125		°C		
老化率 Aging Per Year		@25°C			±3.0	ppm	
工作电压 Input Voltage	Vcc		4.75	5.00	5.25	V	
			3.15	3.30	3.45		
			2.38	2.50	2.63		
			1.71	1.80	1.89		
消耗电流 Input Current	Icc	F=32.768KHz to 50MHz			5	mA	注 2 Note 2
					10		
输出波形 Output Wave			HCMOS, TTL				
负载 Load	L		HCMOS15pF~50pF; 5~10TTL				
占空比 Duty Cycle		At Vcc/2	45		55	%	
上升/下降 时间 Rise/Fall Time	Tr/Tf	F=32.768KHz to 20MHz			3	ns	注 3 Note 3
		F=20MHz to 220MHz			2		
逻辑1输出电平 Logic 1 Level	Voh	TTL	2.4			V	
		HCMOS	90%			Vcc	
逻辑0输出电平 Logic 0 Level	Vol	TTL			0.4	V	
		HCMOS			10%	Vcc	
启振时间 Start-up Time	Ts			2	15	ms	
3态功能 Tristate Function		当引脚1给电压(>2.4V)时,晶振输出标称频率;当引脚1给电压(<0.4V)时,晶振停止输出;当引脚1悬空时,默认高电平,晶振正常工作 Pad #1 input High(>2.4V) or open, Pad #3 Enable: Active Pad #1 input Low (<0.4V), Pad #3 Disable: High impedance					
引脚函数 Pin Function		Pin #1- NC or Tristate Ctr Pin #5-Output	Pin #4-Ground Case Pin #8-Vcc				
温度循环 Tempeaure Cycle		Per MIL-STD-883E, Method 1010.7, Cond. B					
机械冲击 Mechanical Shock		Per MIL-STD-883E, Method 2002.4, Cond .B					
振动 Vibration		Per MIL-STD-883E, Method 2007.3, Cond .A					
泄漏测试 Leak Testing		Per MIL-STD-883E, Method 1014					
可焊性 Solderability		Per MIL-STD-883E, Method 2003					
防潮 Moisture Resistance		Per MIL-STD-202, Method 106					

注释:

- 1: 整体稳定性以25°C为基准, 随着温度的变化频率、负载、老化率也将随之产生变化
  - 2: 取决于负载和频率
  - 3: 上升/下降时间随频率和电源电压的变化而变化
- 所有规格如有更改, 恕不另行通知。

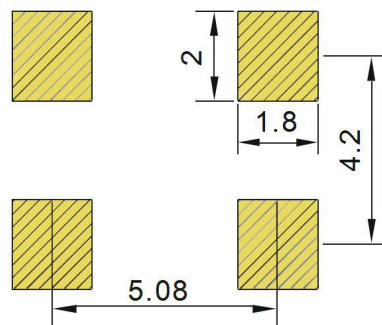
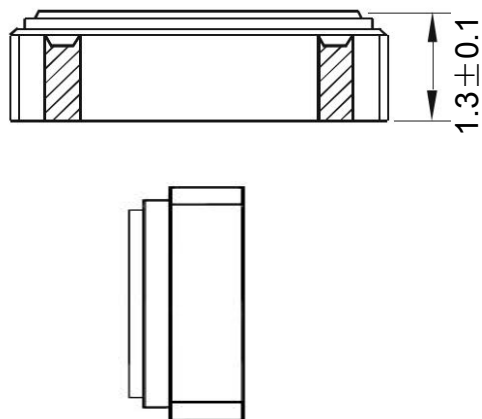
Notes:

- 1: Overall stability including calibration at 25°C, operating temp. range, supply variation, load variation, aging.
  - 2: Current is load and frequency dependent.
  - 3: Rise/Fall time varies with frequency and Supply voltage.
- All specifications are subject to change without notice



推荐的焊盘布局  
Recommended Solder Pad Layout

边视图  
Front View



所有尺寸是典型的，另有规定除外  
All dimensions are typical unless otherwise specified